

PCN Number:	20131024001	PCN Date:	10/28/2013
Title:	Qualification of TI Clark as additional Assembly site for selected VSON packaged products		
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037
Dept:	Quality Services		
Proposed 1st Ship Date:	01/28/2014	Estimated Sample Availability:	11/30/2013
Change Type:	<input checked="" type="checkbox"/> Assembly Site <input checked="" type="checkbox"/> Assembly Materials		

PCN Details

Description of Change:

Qualification of TI Clark (Philippines) as an additional assembly site for below listed devices in the VSON package family. Material differences are noted below:

	SEM	TI Clark
Leadframe	201207/201221	4218176
Mold Compound	202828	4220838
Mount Solder	200757/202954	4208625
Lead Finish	Matte Sn	NiPdAu

Upon expiry of this PCN, TI will combine lead free solutions in a single [standard part number](#), for example; [CSD18532Q5B](#) – can ship with both Matte Sn and NiPdAu.

Reason for Change:

Business Continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Assembly Site		
PSI Technologies (SEM)	Assembly Site Origin (22L)	ASO: PAC
TI Clark	Assembly Site Origin (22L)	ASO: QAB

Sample product shipping label (not actual product label)

G4 = NiPdAu
G3= MATTE Sn

Topside Device marking:

Assembly site code for SEM= E

Assembly site code for TI Clark = I

Product Affected:			
CSD16556Q5B	CSD18502Q5B	CSD18532NQ5B	CSD18532Q5B
CSD17556Q5B			

Qualification Data

This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle: CSD18532Q5B

Package Construction Details

Assembly Site:	TI Clark	Mold Compound:	4208625
# Pins-Designator, Family:	8, DNK	Mount Solder:	4220838
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	Au, 2.0 mils

Qualification: Plan **Test Results**

Reliability Test	Conditions	Sample Size/Fail		
		Lot# 1	Lot# 2	Lot# 3
HTRB	150°C/80% Rated Vds (1000 Hrs)	77/0	77/0	77/0
HTGB	150°C/80% Rated Vgs (1000 Hrs)	77/0	77/0	77/0
**THB	85°C/85%R.H./80% Rated Vds (1000 Hrs)	77/0	77/0	77/0
**Autoclave	121C/100% RH (96 Hrs)	77/0	77/0	77/0
Intermittent Op Life	Delta Tj=100°C, 2 min on/2 min off (10K Cy)	77/0	77/0	77/0
**Temp Cycle	-65°C to 150°C (500 Cy)	77/0	77/0	77/0

Notes **- Preconditioning sequence: Level 1-260C.

Qualification Data

This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle: CSD18502Q5B

Package Construction Details

Assembly Site:	TI Clark	Mold Compound:	4208625
# Pins-Designator, Family:	8, DNK	Mount Solder:	4220838
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	Au, 2.0 mils

Qualification: Plan **Test Results**

Reliability Test	Conditions	Sample Size/Fail		
		Lot# 1	Lot# 2	Lot# 3
HTRB	150°C/80% Rated Vds (1000 Hrs)	77/0	77/0	77/0
HTGB	150°C/80% Rated Vgs (1000 Hrs)	77/0	77/0	77/0
**THB	85°C/85%R.H./80% Rated Vds (1000 Hrs)	77/0	77/0	77/0

Notes **- Preconditioning sequence: Level 1-260C.

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com